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## FDT457N N-Channel Enhancement Mode Field Effect Transistor

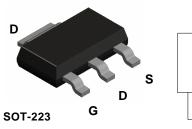
### **General Description**

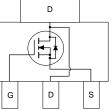
These N-Channel enhancement mode power field effect transistors are produced using ON Semiconductor's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance, provide superior switching performance. These products are well suited to low voltage, low current applications such as notebook computer power management, battery powered circuits, and DC motor control.

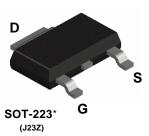
### Features

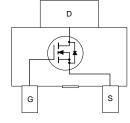
- 5 A, 30 V.  $R_{DS(ON)} = 0.06 \ \Omega \ @ V_{GS} = 10 \ V$  $R_{DS(ON)} = 0.090 \ \Omega \ @ V_{GS} = 4.5 \ V.$
- High density cell design for extremely low R<sub>DS(ON)</sub>.
- High power and current handling capability in a widely used surface mount package.











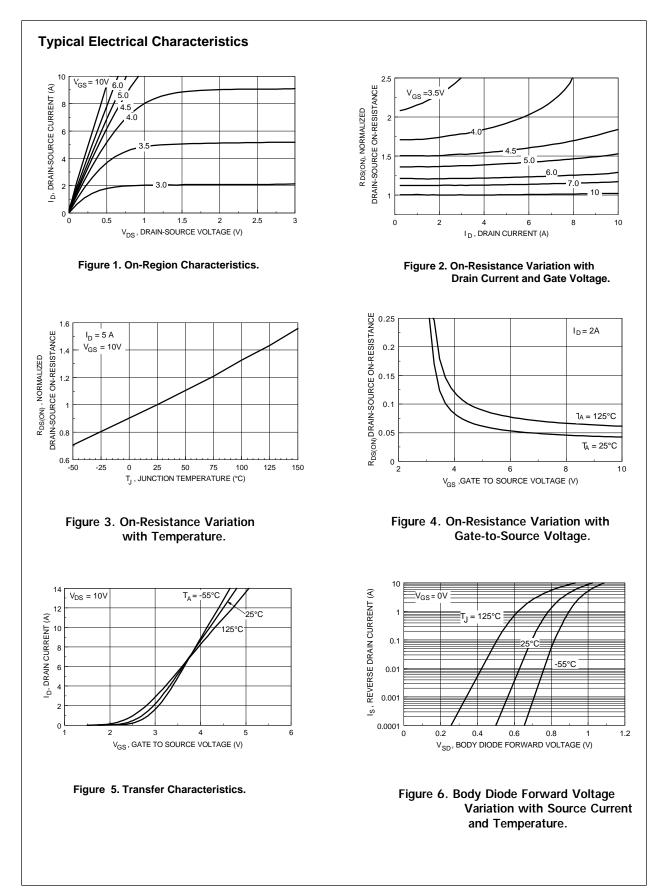
### **Absolute Maximum Ratings** $T_A = 25^{\circ}C$ unless otherwise noted

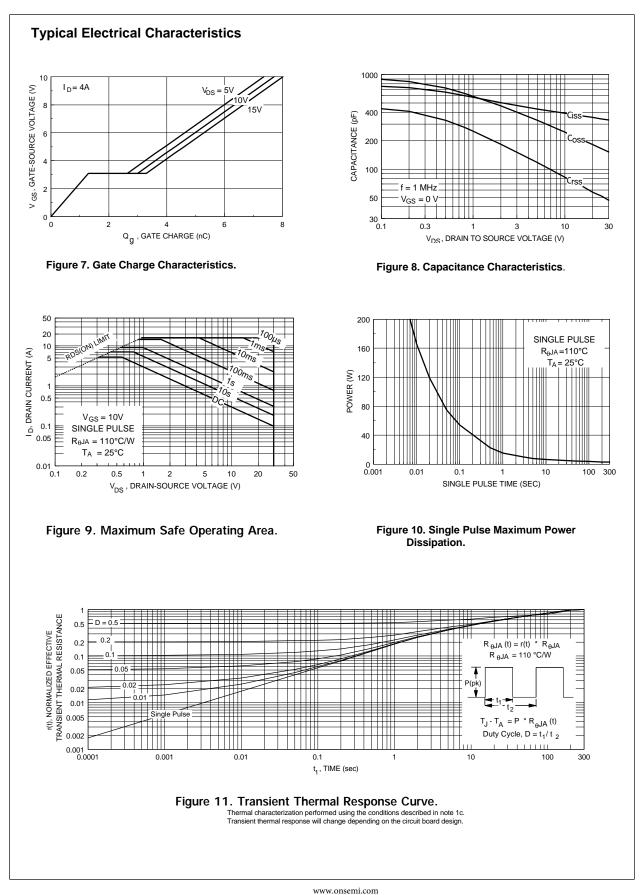
Symbol	Parameter		FDT457N	Units
V <sub>DSS</sub>	Drain-Source Voltage		30	V
V <sub>GSS</sub>	Gate-Source Voltage - Continuous		±20	V
I <sub>D</sub>	Maximum Drain Current - Continuous	(Note 1a)	5	A
	- Pulsed		16	
P <sub>D</sub>	Maximum Power Dissipation	(Note 1a)	3	W
	4)	lote 1b)	1.3	
	4)	lote 1c)	1.1	
T_,T <sub>stg</sub>	Operating and Storage Temperature Rang	je	-65 to 150	°C
THERMA	L CHARACTERISTICS			
R <sub>eja</sub>	Thermal Resistance, Junction-to-Ambient	(Note 1a)	42	°C/W
R <sub>ejic</sub>	Thermal Resistance, Junction-to-Case	(Note 1)	12	°C/W

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Symbol	Parameter	Conditions		Min	Тур	Max	Units
OFF CHAR	ACTERISTICS						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 V, I_{D} = 250 \mu A$		30			V
$\Delta BV_{DSS} / \Delta T_{J}$	Breakdown Voltage Temp. Coefficient	$I_{\rm D}$ = 250 µA, Referenced t	o 25 °C		35		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{\rm DS} = 24  \rm V,  V_{\rm GS} = 0  \rm V$				1	μA
			T, =55°C			10	μA
	Gate - Body Leakage, Forward	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$	, , , , , , , , , , , , , , , , , , ,			100	nA
I <sub>GSSR</sub>	Gate - Body Leakage, Reverse	$V_{GS} = -20 \text{ V}, \text{ V}_{DS} = 0 \text{ V}$				-100	nA
ON CHARA	CTERISTICS (Note 2)						
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	$V_{DS} = V_{GS1}$ $I_{D} = 250 \mu A$		1.6	3	V
$\Delta V_{GS(th)} / \Delta T_J$	Gate Threshold Voltage Temp.Coefficient		$I_{\rm p}$ = 250 µA, Referenced to 25 °C		-4.2		mV/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$			0.043	0.06	Ω
DS(ON)		63 / 0	T_=125°C		0.065	0.1	
		$V_{GS} = 4.5 \text{ V}, I_{D} = 3.8 \text{ A}$	J		0.071	0.09	
I <sub>D(ON)</sub>	On-State Drain Current	$V_{GS} = 10 \text{ V}, \text{ V}_{DS} = 5 \text{ V}$		5			А
g <sub>FS</sub>	Forward Transconductance	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 5 \text{ A}$			5		S
-	HARACTERISTICS	50 . 5					
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			235		pF
C <sub>oss</sub>	Output Capacitance				145		pF
C <sub>rss</sub>	Reverse Transfer Capacitance				50		pF
	CHARACTERISTICS (Note 2)				1		
t <sub>D(on)</sub>	Turn - On Delay Time	$V_{DD} = 10 \text{ V}, \ \text{I}_{D} = 1 \text{ A},$			5	10	ns
t,	Turn - On Rise Time	$V_{GS} = 10 \text{ V}, \text{ R}_{GEN} = 6 \Omega$			12	22	ns
t <sub>D(off)</sub>	Turn - Off Delay Time				12	22	ns
t,	Turn - Off Fall Time				3	8	ns
Q <sub>g</sub>	Total Gate Charge	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 5 \text{ A},$ $V_{GS} = 5 \text{ V}$			4.2	5.9	nC
Q <sub>gs</sub>	Gate-Source Charge				1.3		nC
Q <sub>gd</sub>	Gate-Drain Charge				1.7		nC
-	RCE DIODE CHARACTERISTICS AND MAX	IMUM RATINGS					
l <sub>s</sub>	Maximum Continuous Drain-Source Diode Fo	in-Source Diode Forward Current				2.5	А
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 V, I_{S} = 2.5 A$ (Note 2)			0.85	1.2	V
-	n of the junction-to-case and case-to-ambient thermal resistance w v design while R <sub>gcA</sub> is determined by the user's board design.	where the case thermal reference is define $\psi$	ed as the solder mor	unting surfa Ψ	ce of	the drain p	bins. R <sub>θJC</sub> is

Scale 1 : 1 on letter size paper 2. Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2.0%





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